

ABSTRACT OF THE DISCLOSURE

An underfill system for filling gaps between semiconductor chips and substrates is provided. The underfill system comprises a blower for blowing air, an air duct coupled to the blower, the air duct comprising a main duct coupled to the blower and a plurality of sub-ducts each having an outlet being connected to the main duct and an inlet to be located along one side of the semiconductor chip. A filling material from a dispenser fills the gaps by suction due to the pressure difference between the main duct and the sub-duct. Thus, the present invention shortens the filling time of the underfill process and prevents voids or air bubbles of the filling material from forming within the gap.

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